

CMOS Digital Integrated Circuits Silicon Monolithic

TC7WZ74FU

1. Functional Description

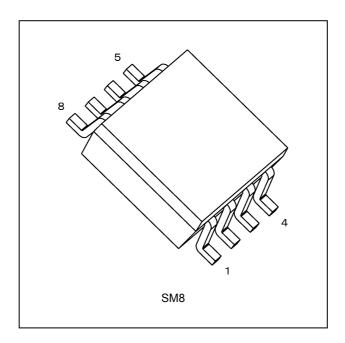
• D-Type Flip Flop with Preset and Clear

2. Features

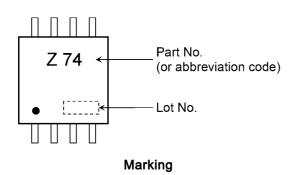
- (1) Wide operating temperature range: $T_{opr} = -40$ to 125 °C (Note 1)
- (2) High output current: ± 24 mA (min) ($V_{CC} = 3.0$ V)
- (3) High speed operation: $t_{pd} = 2.8 \text{ ns (typ.)}$ ($V_{CC} = 5.0 \text{ V}$, $C_L = 50 \text{ pF}$)
- (4) Wide operating voltage range: $V_{\rm CC}$ = 1.65 to 5.5 V
- (5) 5.5 V tolerant inputs
- (6) 5.5 V power down protection output
- (7) Matches the performance of TC74LCX series when operated at $3.3~V~V_{\rm CC}$

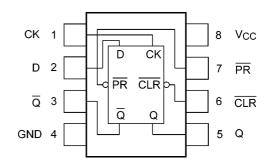
Note 1: For devices with the ordering part number ending in J(CT. T_{opr} = -40 to 85 °C for the other devices.

3. Packaging



4. Marking and Pin Assignment





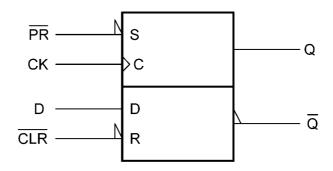
Pin Assignment (Top view)

Start of commercial production

2001-04



5. IEC Logic Symbol



6. Truth Table

	Inp	uts		Out	puts	Function	
CLR	PR	D	СК	Q	Q	1 diliction	
L	Н	Х	Х	L	Н	Clear	
Н	L	Х	Х	Н	L	Preset	
L	L	Х	Х	Н	Н	_	
Н	Н	L		L	Н	_	
Н	Н	Н		Н	L	_	
Н	Н	Х	\Box	Qn	Qn	No Change	

X: Don't care

7. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V _{CC}		-0.5 to 6.0	V
Input voltage	V _{IN}		-0.5 to 6.0	٧
DC output voltage	V _{OUT}	(Note 1)	-0.5 to 6.0	V
		(Note 2)	-0.5 to V _{CC} + 0.5	
Input diode current	I _{IK}		-20	mA
Output diode current	I _{OK}	(Note 3)	-20	
DC output current	I _{OUT}		±50	
V _{CC} /ground current	Icc		±50	mA
Power dissipation	P _D		300	mW
Storage temperature	T _{stg}		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: $V_{CC} = 0 V$

Note 2: High (H) or Low (L) state. I_{OUT} absolute maximum rating must be observed.

Note 3: V_{OUT} < GND

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2021-09-06



8. Operating Ranges (Note)

Characteristics	Symbol	Note	Test Condition	Rating	Unit
Supply voltage	V _{CC}		_	1.65 to 5.5	V
		(Note 1)	_	1.5 to 5.5	
Input voltage	V _{IN}		_	0 to 5.5	V
Output voltage	V _{OUT}	(Note 2)	_	0 to 5.5	V
		(Note 3)	_	0 to V _{CC}	
Operating temperature	T _{opr}	(Note 4)	_	-40 to 125	°C
		(Note 5)	_	-40 to 85	
Input rise and fall time	dt/dv		V_{CC} = 1.8 \pm 0.15 V, 2.5 \pm 0.2 V	0 to 20	ns/V
			V _{CC} = 3.3 ± 0.3 V	0 to 10	1
			V _{CC} = 5.0 ± 0.5 V	0 to 5]

Note: The operating ranges must be maintained to ensure the normal operation of the device.

Unused inputs must be tied to either V_{CC} or GND.

Note 1: Data retention only

Note 2: $V_{CC} = 0 V$

Note 3: High (H) or Low (L) state.

Note 4: For devices with the ordering part number ending in J(CT.

Note 5: For devices except those with the ordering part number ending in J(CT.

9. Electrical Characteristics

9.1. DC Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition		V _{CC} (V)	Min	Тур.	Max	Unit
High-level input voltage	V _{IH}	_		1.65 to 1.8	V _{CC} × 0.75	_	_	V
				2.3 to 5.5	$V_{CC} \times 0.70$	_	_	
Low-level input voltage	V _{IL}	_		1.65 to 1.8	_	_	V _{CC} × 0.25	٧
				2.3 to 5.5	_	_	$V_{CC} \times 0.30$	
High-level output voltage	V _{OH}	V _{IN} = V _{IL} or V _{IH}	I _{OH} = -100 μA	1.65	1.55	1.65	_	٧
				2.3	2.2	2.3		
				3.0	2.9	3.0	_	
				4.5	4.4	4.5	_	
			I _{OH} = -4 mA	1.65	1.29	1.52	_	
			I _{OH} = -8 mA	2.3	1.9	2.15		
			I _{OH} = -16 mA	3.0	2.4	2.8	_	
			I _{OH} = -24 mA	3.0	2.3	2.68	_	
			I _{OH} = -32 mA	4.5	3.8	4.2	_	
Low-level output voltage	V _{OL}	V _{IN} = V _{IL} or V _{IH}	I _{OL} = 100 μA	1.65	_	0.0	0.1	٧
				2.3	_	0.0	0.1	
				3.0	_	0.0	0.1	
				4.5	_	0.0	0.1	
			I _{OL} = 4 mA	1.65	_	0.08	0.24	
			I _{OL} = 8 mA	2.3	_	0.1	0.3	
			I _{OL} = 16 mA	3.0	_	0.15	0.4	
			I _{OL} = 24 mA	3.0	_	0.22	0.55	
			I _{OL} = 32 mA	4.5	_	0.22	0.55	
Input leakage current	I _{IN}	V _{IN} = 5.5 V or GND		0 to 5.5	_	_	±1	μА
Power-OFF leakage current	I _{OFF}	V _{IN} , V _{OUT} = 5.5 V		0	_	_	1	μА
Quiescent supply current	I _{CC}	V _{IN} = 5.5 V or GND		1.65 to 5.5	_	_	1	μА

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9.2. DC Characteristics (Unless otherwise specified, T_a = -40 to 85 °C)

Characteristics	Symbol	Test Condition		V _{CC} (V)	Min	Max	Unit
High-level input voltage	V _{IH}	_		1.65 to 1.8	$V_{CC} \times 0.75$	_	V
				2.3 to 5.5	V _{CC} × 0.70	_	
Low-level input voltage	V _{IL}	_		1.65 to 1.8	_	V _{CC} × 0.25	V
				2.3 to 5.5	_	V _{CC} × 0.30	
High-level output voltage	V _{OH}	V _{IN} = V _{IL} or V _{IH}	I _{OH} = -100 μA	1.65	1.55	_	V
				2.3	2.2	_	
				3.0	2.9	_	
				4.5	4.4	_	
			I _{OH} = -4 mA	1.65	1.29	_	
			I _{OH} = -8 mA	2.3	1.9	_	
			I _{OH} = -16 mA	3.0	2.4	_	
			I _{OH} = -24 mA	3.0	2.3	_	
			I _{OH} = -32 mA	4.5	3.8	_	
Low-level output voltage	V _{OL}	V _{IN} = V _{IL} or V _{IH}	I _{OL} = 100 μA	1.65	_	0.1	V
				2.3	_	0.1	
				3.0	_	0.1	
				4.5	_	0.1	
			I _{OL} = 4 mA	1.65	_	0.24	
			I _{OL} = 8 mA	2.3	_	0.3	
			I _{OL} = 16 mA	3.0	_	0.4	
			I _{OL} = 24 mA	3.0	_	0.55	
			I _{OL} = 32 mA	4.5	_	0.55	
Input leakage current	I _{IN}	V _{IN} = 5.5 V or GND		0 to 5.5	_	±10	μА
Power-OFF leakage current	I _{OFF}	V _{IN} , V _{OUT} = 5.5 V		0	_	10	μА
Quiescent supply current	I _{CC}	V _{IN} = 5.5 V or GND		1.65 to 5.5	_	10	μА

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9.3. DC Characteristics (Note) (Unless otherwise specified, T_a = -40 to 125 °C)

Characteristics	Symbol	Test Condition	1	V _{CC} (V)	Min	Max	Unit
High-level input voltage	V _{IH}	_		1.65 to 1.8	$V_{CC} \times 0.75$	_	V
				2.3 to 5.5	V _{CC} × 0.70	_	
Low-level input voltage	V _{IL}	_		1.65 to 1.8	_	V _{CC} × 0.25	V
				2.3 to 5.5	_	$V_{CC} \times 0.30$	
High-level output voltage	V _{OH}	V _{IN} = V _{IL} or V _{IH}	I _{OH} = -100 μA	1.65	1.55	_	V
				2.3	2.2	_	
				3.0	2.9	_	
				4.5	4.4	_	
			I _{OH} = -4 mA	1.65	0.95	_	
			I _{OH} = -8 mA	2.3	1.7	_	
			I _{OH} = -16 mA	3.0	2.2	_	
			I _{OH} = -24 mA	3.0	2.0	_	
			I _{OH} = -32 mA	4.5	3.4	_	
Low-level output voltage	V _{OL}	V _{IN} = V _{IL} or V _{IH}	I _{OL} = 100 μA	1.65	_	0.1	V
				2.3	_	0.1	
				3.0	_	0.1	
				4.5	_	0.1	
			I _{OL} = 4 mA	1.65	_	0.7	
			I _{OL} = 8 mA	2.3	_	0.45	
			I _{OL} = 16 mA	3.0		0.6	
			I _{OL} = 24 mA	3.0		0.8	
			I _{OL} = 32 mA	4.5	_	0.8	
Input leakage current	I _{IN}	V _{IN} = 5.5 V or GND		0 to 5.5	_	±20	μΑ
Power-OFF leakage current	I _{OFF}	V _{IN} , V _{OUT} = 5.5 V		0		100	μА
Quiescent supply current	I _{CC}	V _{IN} = 5.5 V or GND		1.65 to 5.5		100	μА

Note: For devices with the ordering part number ending in J(CT.

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9.4. AC Characteristics (Unless otherwise specified, T_a = 25 °C, Input: t_r = t_f = 3 ns)

Characteristics	Symbol	Note	Test Condition	V _{CC} (V)	C _L (pF)	Min	Тур.	Max	Unit
Maximum clock frequency	f _{MAX}		R _L = 500 Ω	1.8 ± 0.15	50	51	_	_	MHz
				2.5 ± 0.2		130	_	_	
				3.3 ± 0.3		200	_	_	
				5.0 ± 0.5		200	_	_	
Propagation delay time	t _{PLH} ,t _{PHL}		$R_L = 1 M\Omega$	1.8 ± 0.15	15	2.5	10.0	18.0	ns
(CK-Q,Q)				2.5 ± 0.2		2.0	4.9	7.5	
				3.3 ± 0.3		1.5	3.3	4.8	
				5.0 ± 0.5		1.0	2.4	3.5	
			R _L = 500 Ω	3.3 ± 0.3	50	2.0	4.3	5.7	
				5.0 ± 0.5		1.5	2.8	4.0	
Propagation delay time	t _{PLH} ,t _{PHL}		$R_L = 1 M\Omega$	1.8 ± 0.15	15	2.5	10.0	17.0	ns
(CLR,PR-Q,Q)				2.5 ± 0.2		2.0	5.0	7.3	
				3.3 ± 0.3		1.5	3.4	4.8	
				5.0 ± 0.5		1.5	2.2	3.5	
			R _L = 500 Ω	3.3 ± 0.3	50	2.0	4.3	5.7	
				5.0 ± 0.5		1.0	3.1	3.9	
Minimum setup time	t _s		R _L = 500 Ω	2.5 ± 0.2	50	3.4	_		ns
				3.3 ± 0.3		2.1	_		
				5.0 ± 0.5		1.5			
Minimum hold time	t _h		R _L = 500 Ω	2.5 ± 0.2	50	2.4			ns
				3.3 ± 0.3		1.4			
				5.0 ± 0.5		1.0			
Minimum pulse width (CK)	$t_{W(L)}, t_{W(H)}$		R _L = 500 Ω	2.5 ± 0.2	50	3.0			ns
				3.3 ± 0.3		3.0			
				5.0 ± 0.5		3.0			
Minimum pulse width	t _{W(L)}		R _L = 500 Ω	2.5 ± 0.2	50	3.0			ns
(CLR,PR)				3.3 ± 0.3		3.0			
				5.0 ± 0.5		3.0			
Minimum removal time	t _{rem}		R _L = 500 Ω	2.5 ± 0.2	50	3.6			ns
				3.3 ± 0.3		2.2	_		
				5.0 ± 0.5		1.3			
Input capacitance	C _{IN}		_	0 to 5.5	_		3.0	10	pF
Output capacitance	C _{OUT}		_	0 to 5.5	_	_	5.0		pF
Power dissipation	C _{PD}	(Note 1)	_	3.3	_	_	30	_	pF
capacitance				5.5		_	47	_	

Note 1: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation. $I_{CC(opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}$

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9.5. AC Characteristics (Unless otherwise specified, $T_a = -40$ to 85 °C, Input: $t_r = t_f = 3$ ns)

Characteristics	Symbol	Test Condition	V _{CC} (V)	C _L (pF)	Min	Max	Unit
Maximum clock frequency	f _{MAX}	RL = 500 Ω	1.8 ± 0.15	50	38	_	MHz
			2.5 ± 0.2		100	_	
			3.3 ± 0.3]	150	_	
			5.0 ± 0.5]	180	_	
Propagation delay time	t _{PLH} ,t _{PHL}	RL = 1 MΩ	1.8 ± 0.15	15	2.1	23.0	ns
(CK-Q,Q)			2.5 ± 0.2]	1.7	9.0	
			3.3 ± 0.3		1.3	5.6	
			5.0 ± 0.5		1.0	3.9	
		RL = 500 Ω	3.3 ± 0.3	50	1.5	7.0	
			5.0 ± 0.5	1	1.3	4.4	
Propagation delay time	t _{PLH} ,t _{PHL}	RL = 1 MΩ	1.8 ± 0.15	15	2.1	21.0	ns
$(\overline{CLR},\overline{PR}-Q,\overline{Q})$			2.5 ± 0.2	1	1.7	8.8	
			3.3 ± 0.3		1.3	5.6	
			5.0 ± 0.5	1	1.0	3.9	
		RL = 500 Ω	3.3 ± 0.3	50	1.5	7.0	
			5.0 ± 0.5	1	1.0	4.3	
Minimum setup time	t _s	RL = 500 Ω	2.5 ± 0.2	50	4.1	_	ns
			3.3 ± 0.3	1	2.5	_	
			5.0 ± 0.5	1	1.7	_	
Minimum hold time	t _h	RL = 500 Ω	2.5 ± 0.2	50	2.9	_	ns
			3.3 ± 0.3	1	1.5	_	
			5.0 ± 0.5	1	1.1	_	
Minimum pulse width (CK)	$t_{W(L)}, t_{W(H)}$	RL = 500 Ω	2.5 ± 0.2	50	3.6	_	ns
			3.3 ± 0.3	1	3.3	_	
			5.0 ± 0.5	1	3.2	_	
Minimum pulse width	t _{W(L)}	RL = 500 Ω	2.5 ± 0.2	50	3.6	_	ns
(CLR,PR)			3.3 ± 0.3	1	3.3	_	
			5.0 ± 0.5]	3.2	_	1
Minimum removal time	t _{rem}	RL = 500 Ω	2.5 ± 0.2	50	4.4	_	ns
			3.3 ± 0.3	1	2.5	_	1
			5.0 ± 0.5	1	1.4	_	1

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9.6. AC Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to 125 °C, Input: $t_r = t_f = 3$ ns)

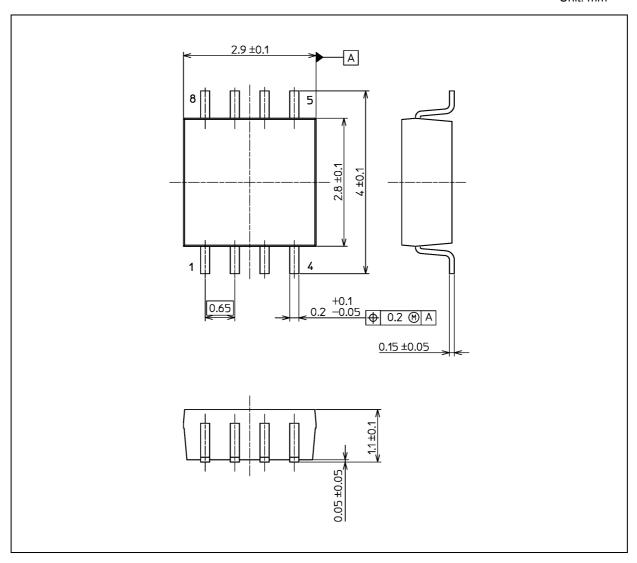
Characteristics	Symbol	Test Condition	V _{CC} (V)	C _L (pF)	Min	Max	Unit
Maximum clock frequency	f _{MAX}	RL = 500 Ω	1.8 ± 0.15	50	34	_	MHz
			2.5 ± 0.2		90	_	
			3.3 ± 0.3]	135	_	
			5.0 ± 0.5]	162	_	
Propagation delay time	t _{PLH} ,t _{PHL}	RL = 1 MΩ	1.8 ± 0.15	15	2.1	26.0	ns
(CK-Q,Q)			2.5 ± 0.2]	1.7	10.0	
			3.3 ± 0.3		1.3	6.2	
			5.0 ± 0.5		1.0	4.3	
		RL = 500 Ω	3.3 ± 0.3	50	1.5	8.8	
			5.0 ± 0.5	1	1.3	4.9	
Propagation delay time	t _{PLH} ,t _{PHL}	RL = 1 MΩ	1.8 ± 0.15	15	2.1	24.0	ns
$(\overline{CLR},\overline{PR}-Q,\overline{Q})$			2.5 ± 0.2	1	1.7	9.7	
			3.3 ± 0.3		1.3	6.2	
			5.0 ± 0.5	1	1.0	4.3	
		RL = 500 Ω	3.3 ± 0.3	50	1.5	7.7	
			5.0 ± 0.5		1.0	4.8	
Minimum setup time	t _s	RL = 500 Ω	2.5 ± 0.2	50	4.1	_	ns
			3.3 ± 0.3	1	2.5	_	
			5.0 ± 0.5	1	1.7	_	
Minimum hold time	t _h	RL = 500 Ω	2.5 ± 0.2	50	2.9	_	ns
			3.3 ± 0.3	1	1.5	_	
			5.0 ± 0.5	1	1.1	_	
Minimum pulse width (CK)	$t_{W(L)}, t_{W(H)}$	RL = 500 Ω	2.5 ± 0.2	50	3.6	_	ns
			3.3 ± 0.3	1	3.3	_	
			5.0 ± 0.5	1	3.2	_	
Minimum pulse width	t _{W(L)}	RL = 500 Ω	2.5 ± 0.2	50	3.6	_	ns
(CLR,PR)			3.3 ± 0.3	1	3.3	_	
			5.0 ± 0.5]	3.2	_	
Minimum removal time	t _{rem}	RL = 500 Ω	2.5 ± 0.2	50	4.4	_	ns
			3.3 ± 0.3]	2.5	_	
			5.0 ± 0.5]	1.4	_	

Note: For devices with the ordering part number ending in J(CT.



Package Dimensions

Unit: mm



Weight: 21 mg (typ.)

	Package Name(s)
JEDEC: SOT-505	
Nickname: SM8	



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